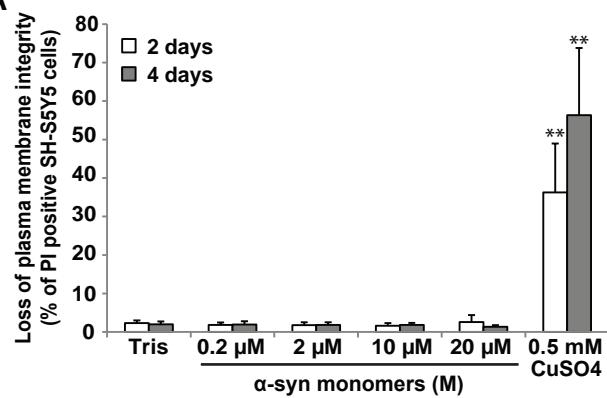
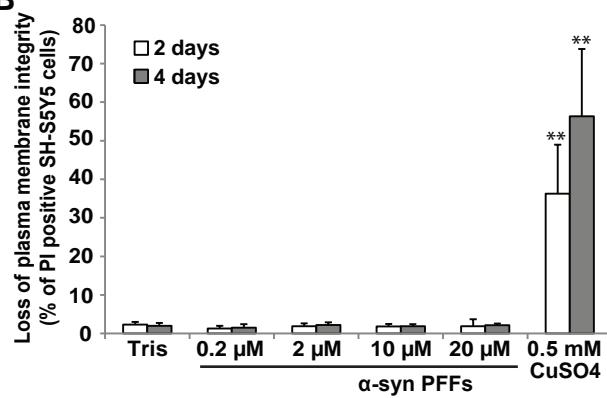


Figure S1

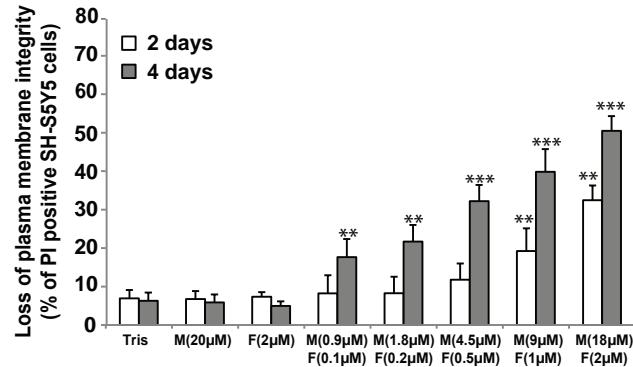
A



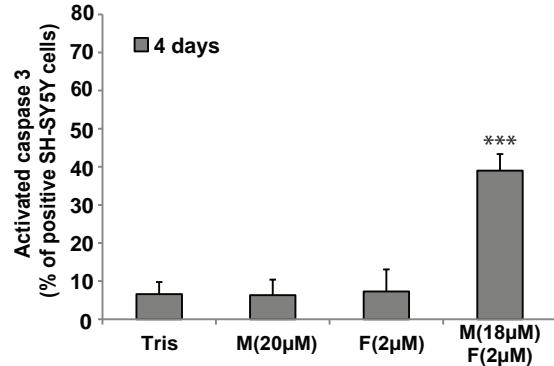
B



C



D



E

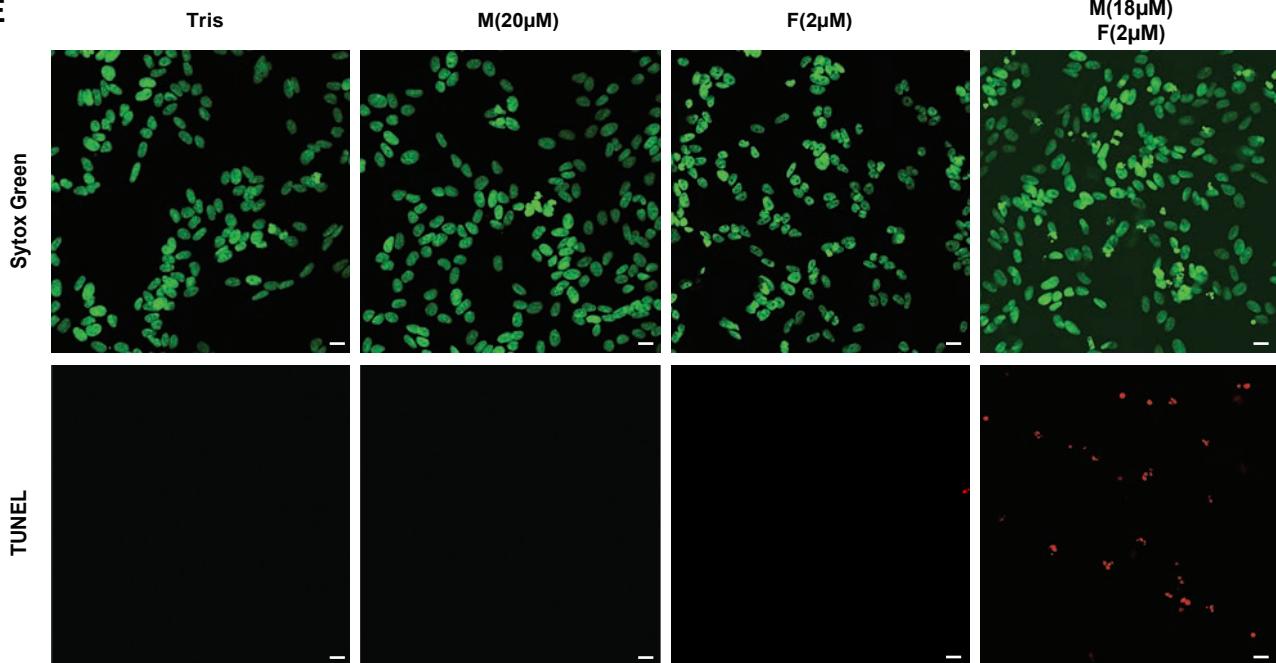


Figure S2

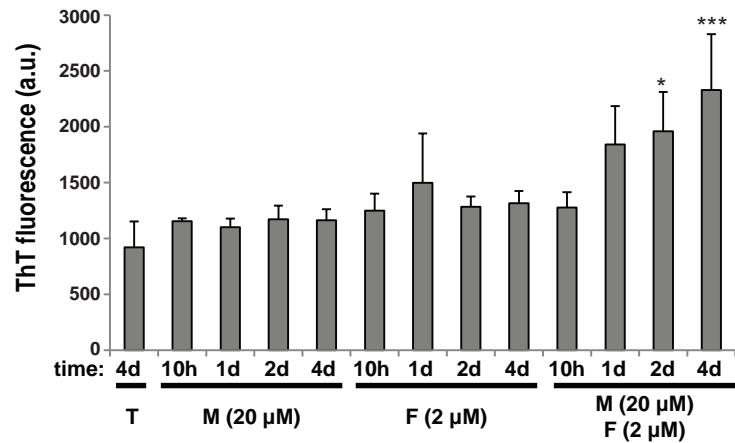


Figure S3

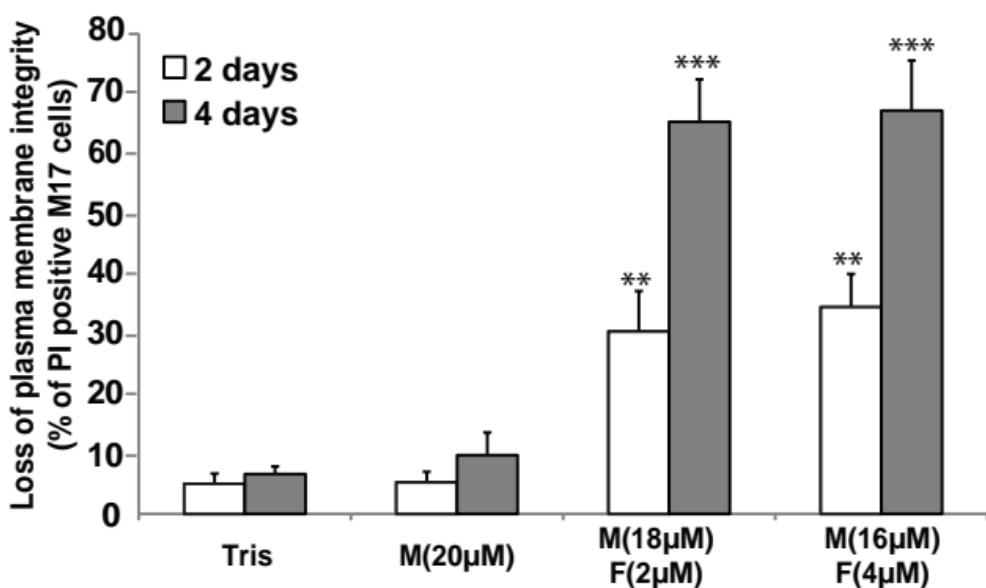
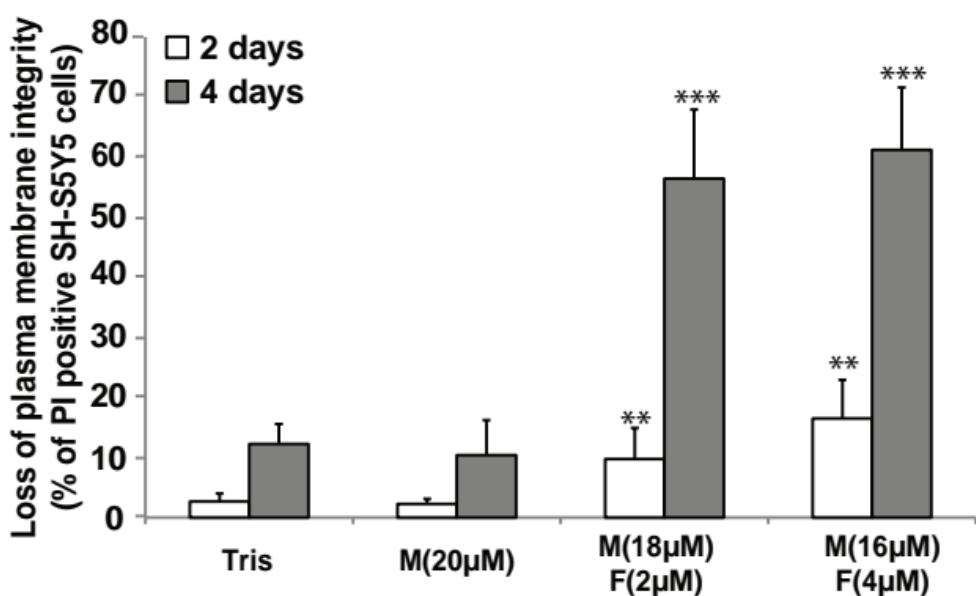
A**B**

Figure S4

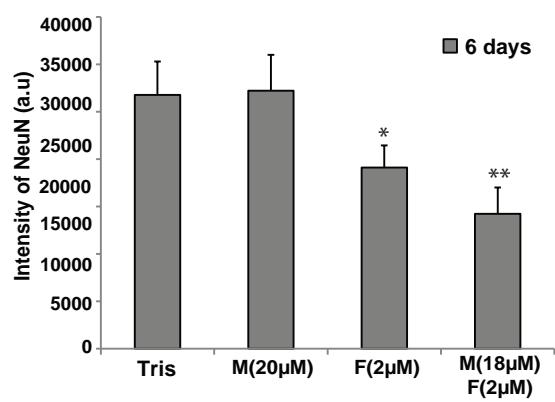


Figure S5

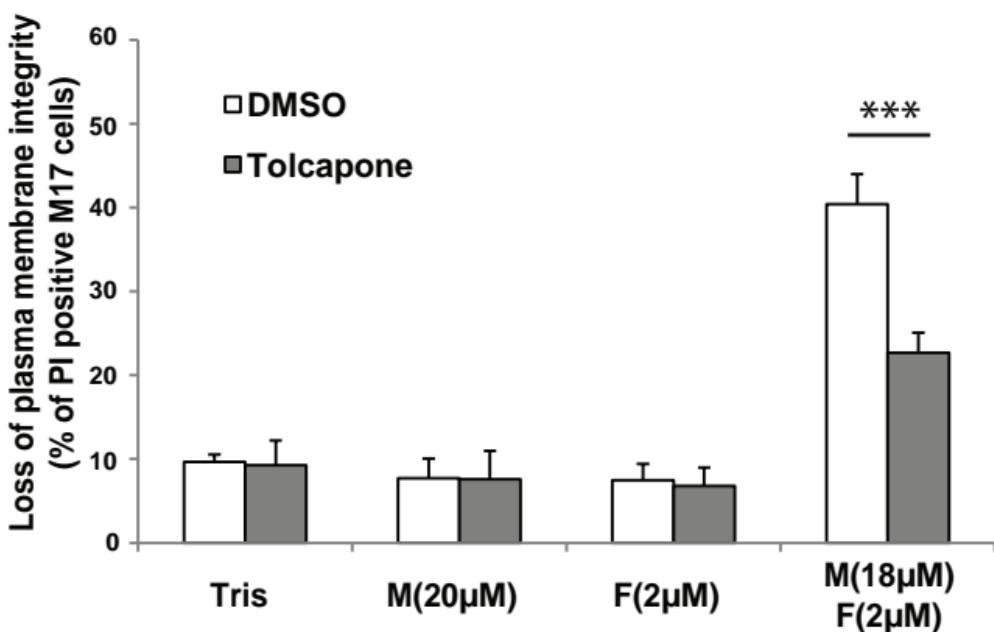
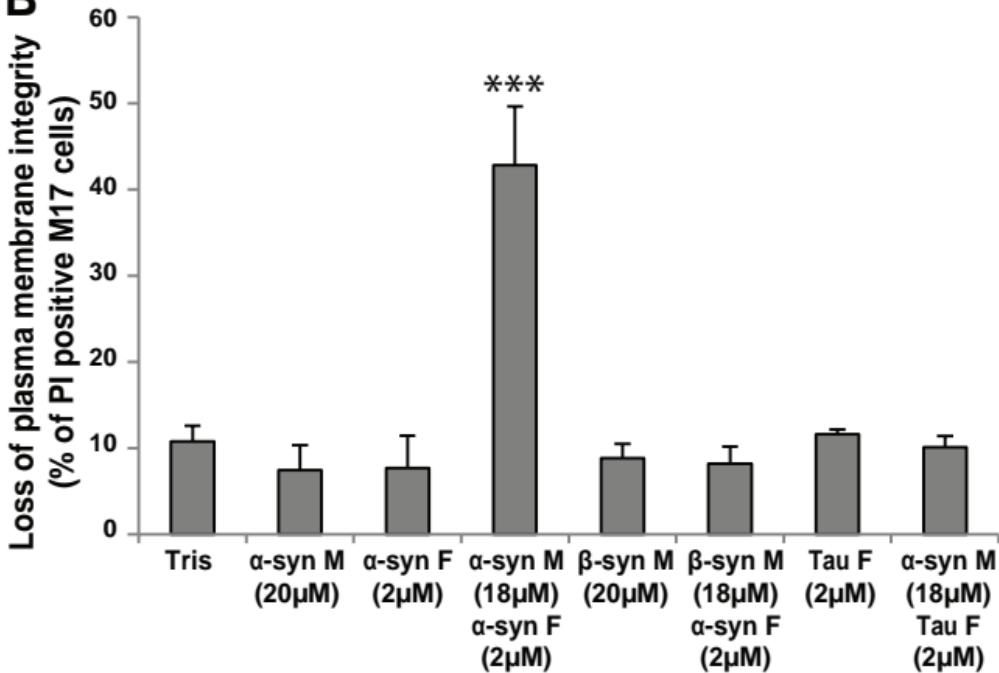
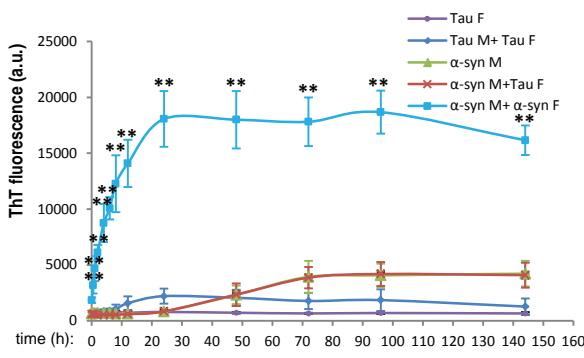
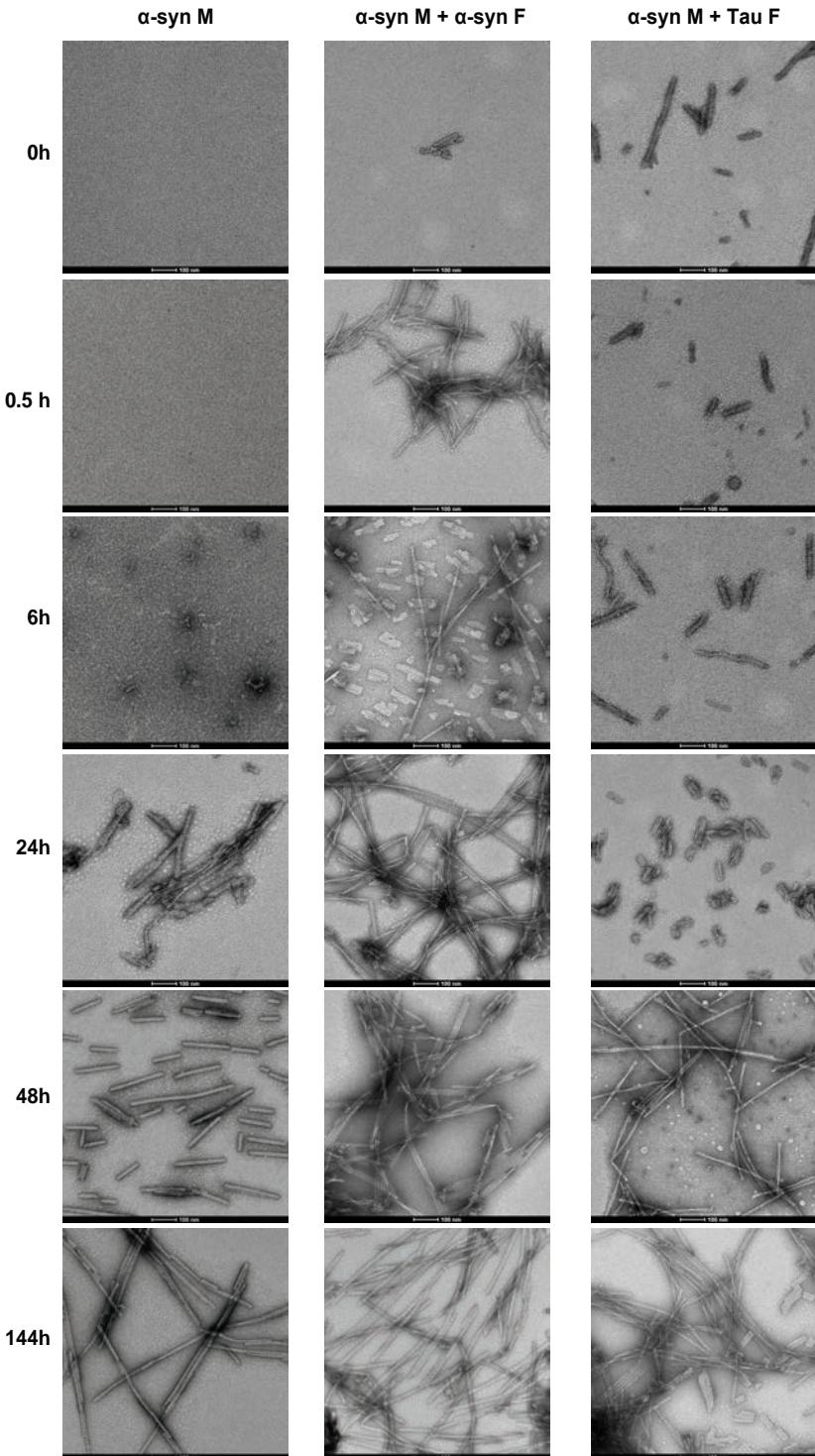
A**B**

Figure S6

A



C



B

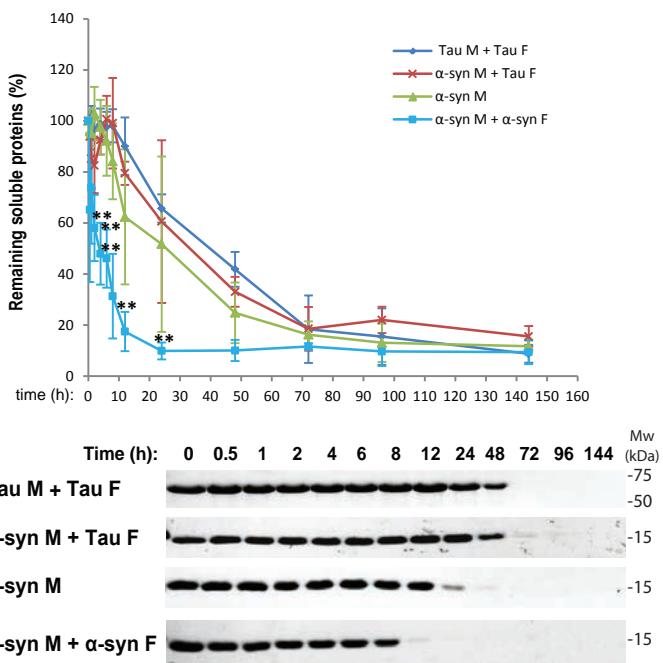
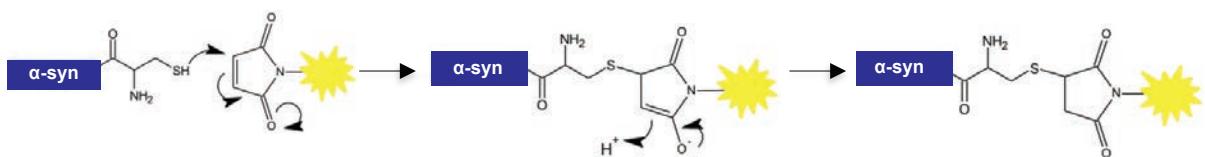
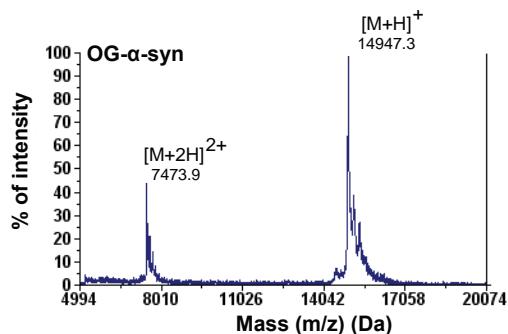


Figure S7

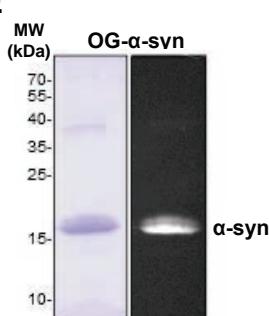
A



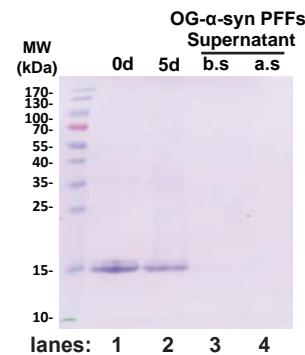
B



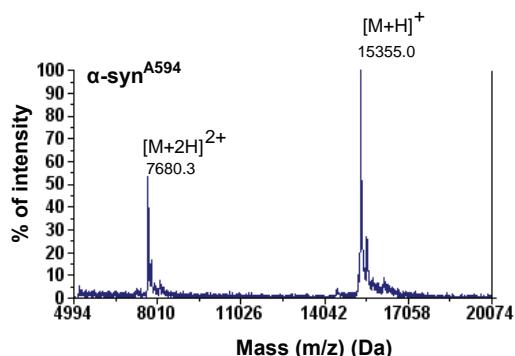
E



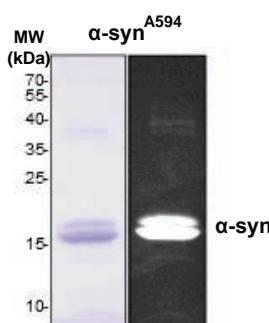
H



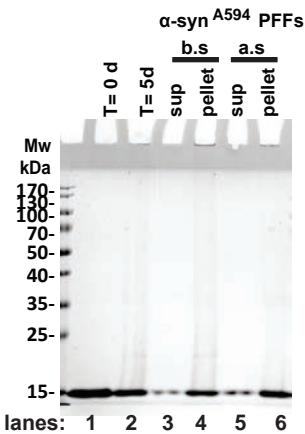
C



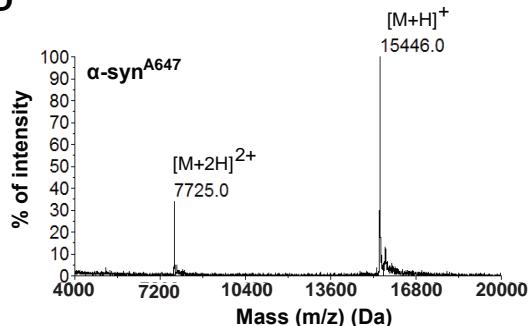
F



I



D



G

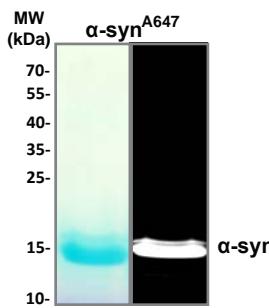


Figure S8

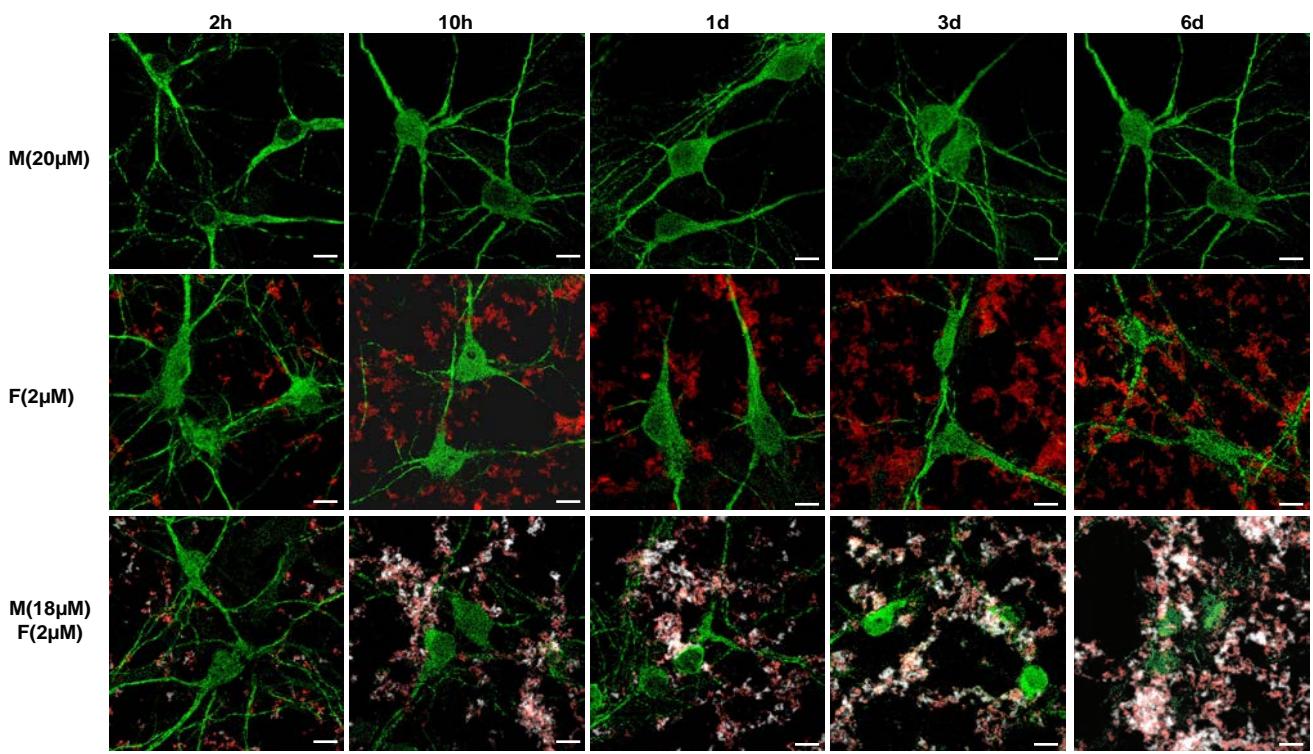


Figure S9

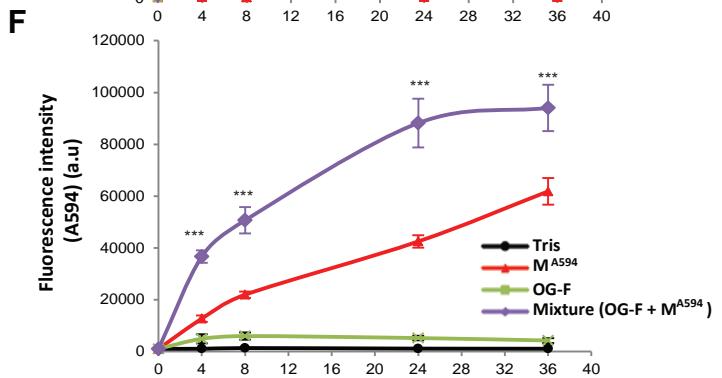
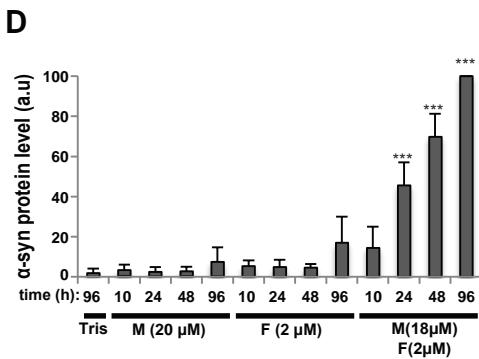
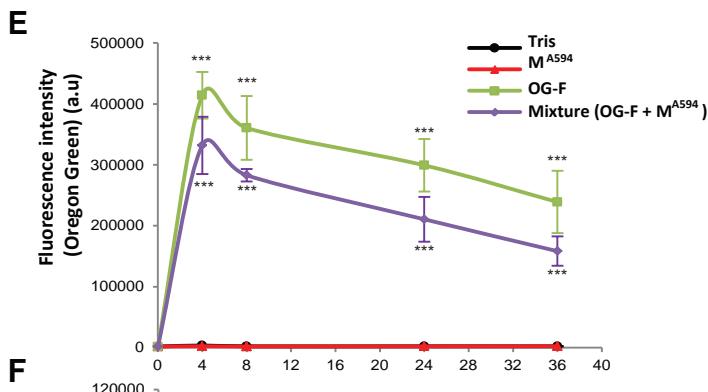
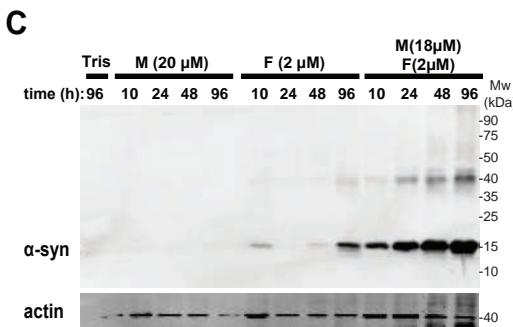
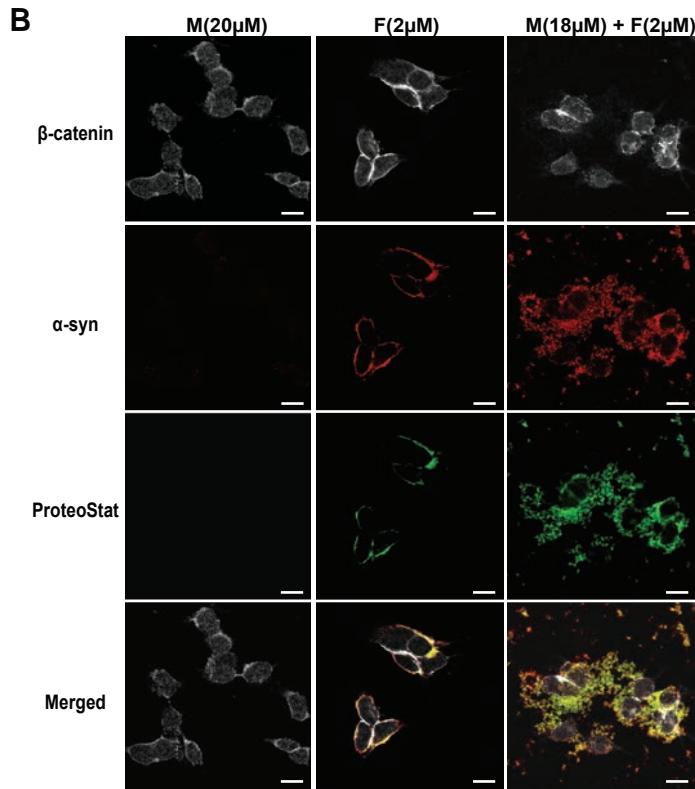
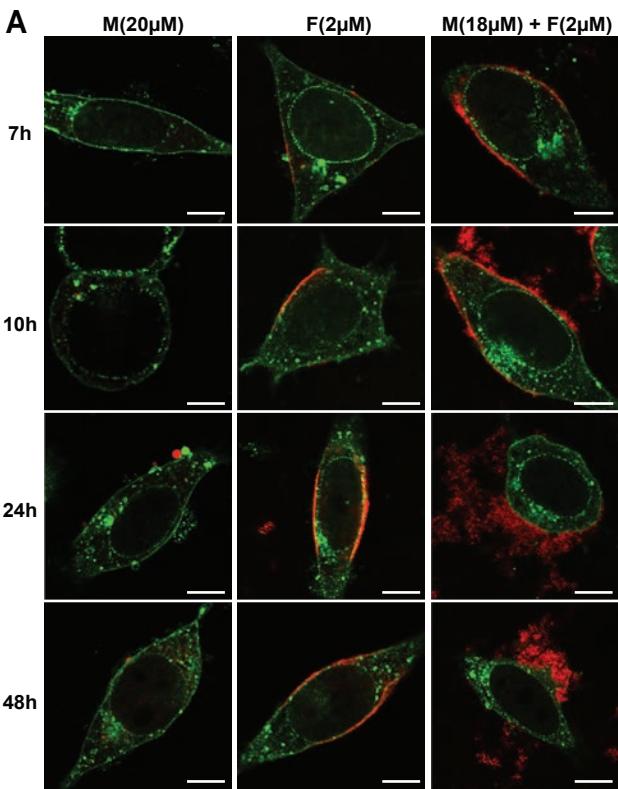
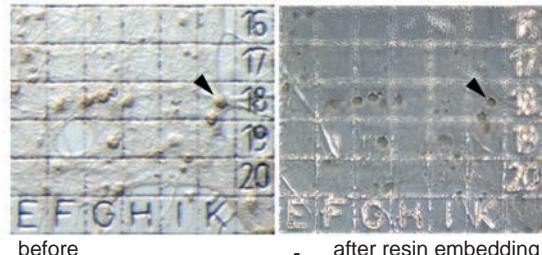
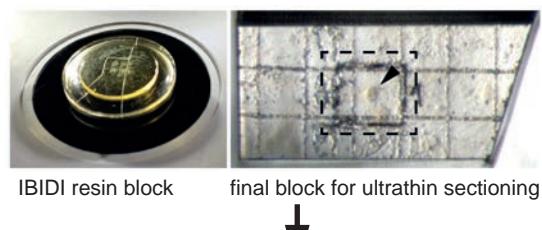
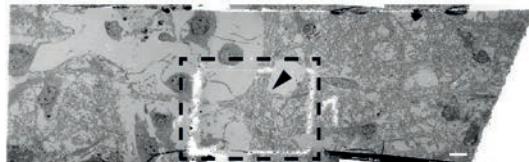


Figure S10

A**Confocal microscopy imaging (1)****Processing for EM and resin embedding (2)****Marking cell position on the resin block surface and trimming the cutting face (3)****TEM imaging (4)****B**

Tris

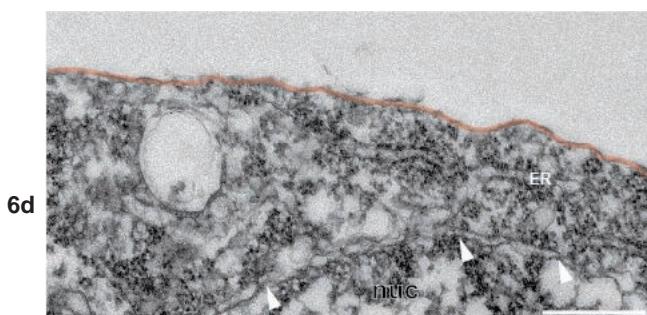
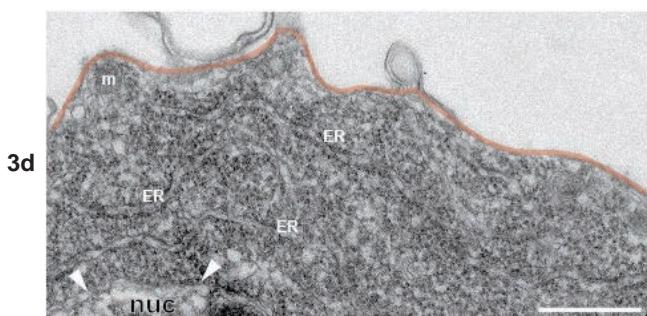
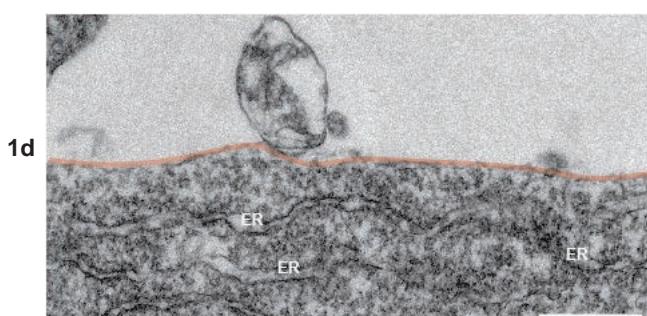


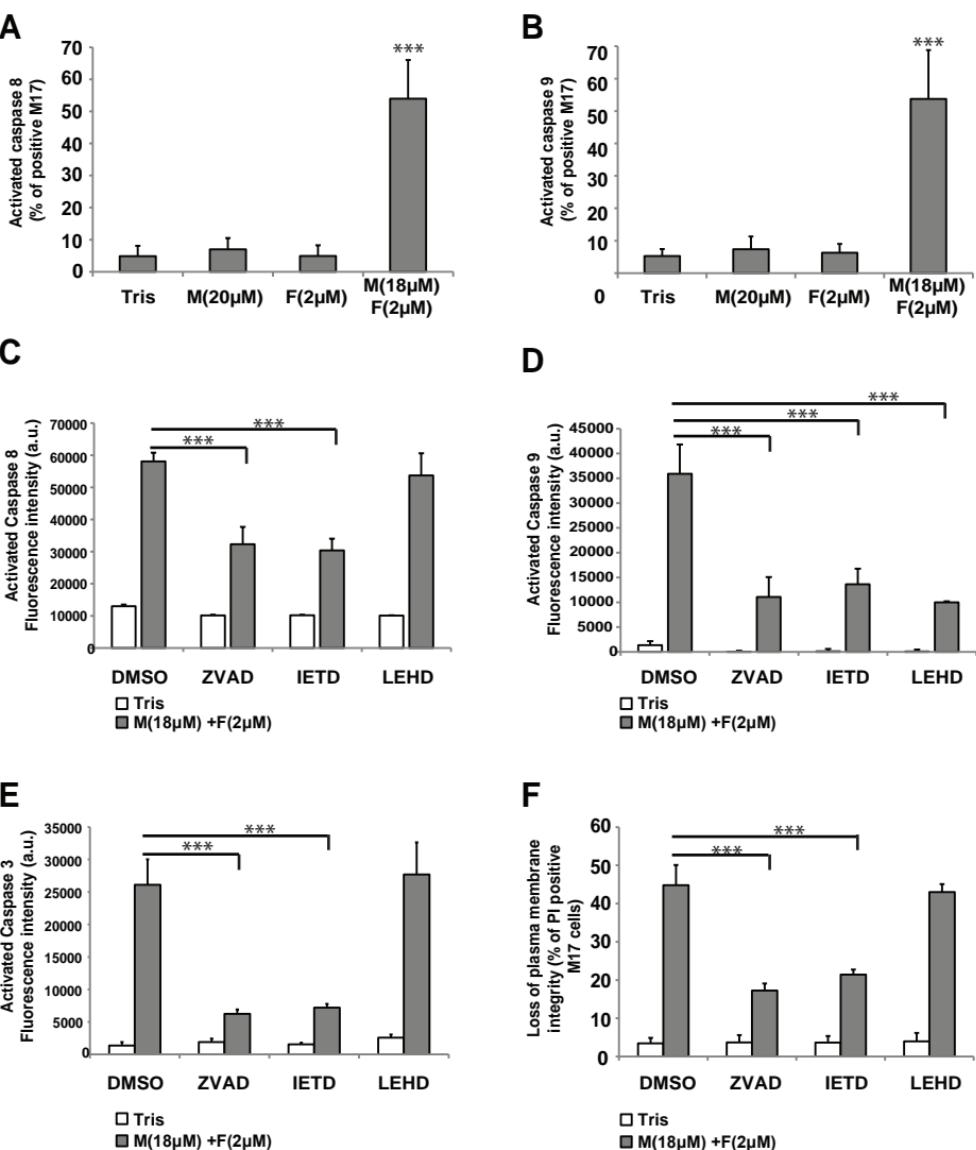
Figure S11

Figure S12

